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February 2016

FGA40S65SH 650 V, 40 A Field Stop Trench IGBT

Features

- Maximum Junction Temperature : T_J = 175°C
- · Positive Temperaure Co-efficient for Easy Parallel Operating
- · High Current Capability
- Low Saturation Voltage: $V_{CE(sat)} = 1.4 \text{ V (Typ.)} @ I_C = 40 \text{ A}$
- 100% of the Parts tested for I_{LM}(1)
- · High Input Impedance
- · Tighten Parameter Distribution
- · RoHS Compliant

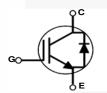
General Description

Using Fairchild's proprietary trench design and advanced field stop IGBT technology, 650V field stop offers superior conduction and switching performance and easy parallel operation. This device is well suited for the resonant or soft switching application such as induction heating and MWO.

Applications

· Induction Heating, MWO





Absolute Maximum Ratings

Symbol	Description		FGA40S65SH	Unit	
V _{CES}	Collector to Emitter Voltage		650	V	
V_{GES}	Gate to Emitter Voltage		± 20	V	
	Transient Gate to Emitter Voltage		± 30	V	
I _C	Collector Current	$@T_C = 25^{\circ}C$	80	Α	
.0	Collector Current	$@ T_C = 100^{\circ}C$	40	Α	
I _{LM} (1)	Pulsed Collector Current	@ T _C = 25°C	120	Α	
I _{CM} (2)	Pulsed Collector Current		120	Α	
I _F	Diode Forward Current	@ T _C = 25°C	40	Α	
	Diode Forward Current	$@ T_C = 100^{\circ}C$	20	A	
I _{FM}	Pulsed Diode Maximum Forward Current		240	A	
P _D	Maximum Power Dissipation	@ T _C = 25°C	268	W	
	Maximum Power Dissipation	$@ T_C = 100^{\circ}C$	134	W	
T _J	Operating Junction Temperature		-55 to +175	°C	
T _{stg}	Storage Temperature Range		-55 to +175	°C	
TL	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds		300	°C	

Thermal Characteristics

Symbol	Parameter	FGA40S65SH	Unit	
R _{θJC} (IGBT)	Thermal Resistance, Junction to Case, Max.	0.56	°C/W	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	40	°C/W	

- 1. V_{CC} = 400 V, V_{GE} = 15 V, I_{C} = 120 A, R_{G} = 35 Ω , Inductive Load 2. Repetitive rating: Pulse width limited by max. junction temperature

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Qty per Tube
FGA40S65SH	FGA40S65SH	TO-3PN	-	-	30

Electrical Characteristics of the IGBT $T_C = 25$ °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	eteristics					
BV _{CES}	Collector to Emitter Breakdown Voltage	V _{GE} = 0 V, I _C = 1 mA	650	-	-	V
$\Delta BV_CES \ / \ \Delta T_J$	Temperature Coefficient of Breakdown Voltage	$V_{GE} = 0 \text{ V}, I_C = 1 \text{ mA}$	-	0.65	-	V/°C
I _{CES}	Collector Cut-Off Current	$V_{CE} = V_{CES}, V_{GE} = 0 V$	-	-	250	μΑ
I _{GES}	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0 V$	/-	-	± 400	nA
On Charac	eteristics					
V _{GE(th)}	G-E Threshold Voltage	$I_C = 40 \text{ mA}, V_{CE} = V_{GE}$	4.0	5.3	7.5	V
(-)		I _C = 40 A, V _{GE} = 15 V	-	1.40	1.81	V
V _{CE(sat)}		I _C = 40 A, V _{GE} = 15 V, T _C = 175°C	- \	1.65	-	V
		$I_F = 20 \text{ A}, T_C = 25^{\circ}\text{C}$	-	1.45	1.95	V
V_{FM}	Diode Forward Voltage	I _F = 20 A, T _C = 175°C	-	1.65	-	V
Dynamic C	Characteristics		ı			
C _{ies}	Input Capacitance		-	2012	-	pF
C _{oes}	Output Capacitance	$V_{CE} = 30 \text{ V}, V_{GE} = 0 \text{ V},$ f = 1 MHz	-	49	-	pF
C _{res}	Reverse Transfer Capacitance	1 - 1 1011 12	-	26	-	pF
Switching	Characteristics					
T _{d(on)}	Turn-On Delay Time		-	19.2	-	ns
T _r	Rise Time		-	65.6	-	ns
T _{d(off)}	Turn-Off Delay Time	V_{CC} = 400 V, I_{C} = 40 A, R_{G} = 6 Ω , V_{GE} = 15 V, Resistive Load, T_{C} = 25°C	- /	68.8	-	ns
T _f	Fall Time		-	96.8	-	ns
E _{on}	Turn-On Switching Loss		_	194	-	uJ
E _{off}	Turn-Off Switching Loss		-	388	-	uJ
E _{ts}	Total Switching Loss		-	592	- /-	uJ
T _{d(on)}	Turn-On Delay Time		-	19.2	-	ns
T _r	Rise Time		-	87.2	- //	ns
$T_{d(off)}$	Turn-Off Delay Time	V_{CC} = 400 V, I_{C} = 40 A, R_{G} = 6 Ω , V_{GE} = 15 V, ResistiveLoad, T_{C} = 175°C	-	75.2	-	ns
T _f	Fall Time		-	158	- \	ns
E _{on}	Turn-On Switching Loss		-	292	-	uJ
E _{off}	Turn-Off Switching Loss		-	633	-	uJ
E _{ts}	Total Switching Loss		-	925	-	uJ
Qg	Total Gate Charge	V 400 V I 40 A	-	73	-	nC
Q _{ge}	Gate to Emitter Charge	$V_{CE} = 400 \text{ V}, I_{C} = 40 \text{ A},$ $V_{GE} = 15 \text{ V}$	-	13	-	nC
Q _{gc}	Gate to Collector Charge		-	28	-	nC

Typical Performance Characteristics

Figure 1. Typical Output Characteristics

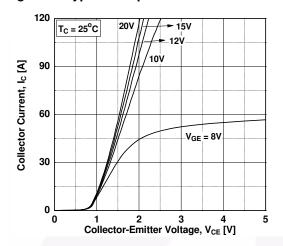


Figure 3. Typical Saturation Voltage Characteristics

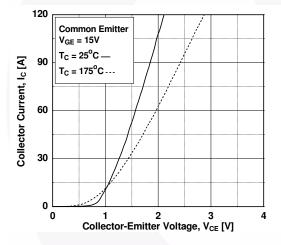


Figure 5. Saturation Voltage vs. V_{GE}

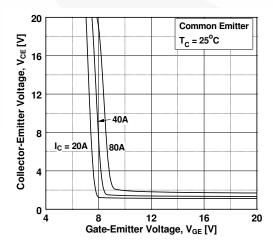


Figure 2. Typical Output Characteristics

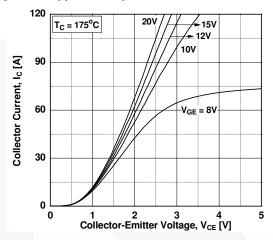


Figure 4. Saturation Voltage vs. Case
Temperature at Variant Current Level

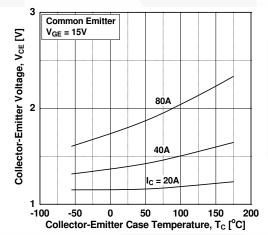
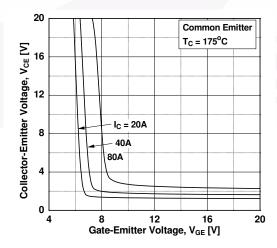


Figure 6. Saturation Voltage vs. V_{GE}



Typical Performance Characteristics

Figure 7. Capacitance Characteristics

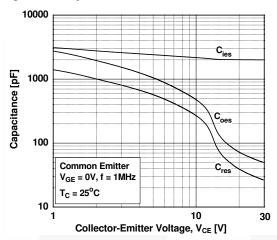


Figure 9. Turn-on Characteristics vs.
Gate Resistance

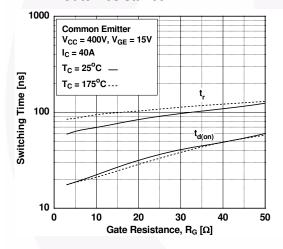


Figure 11. Switching Loss vs.
Gate Resistance

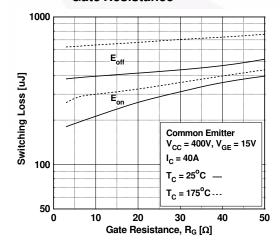


Figure 8. Gate charge Characteristics

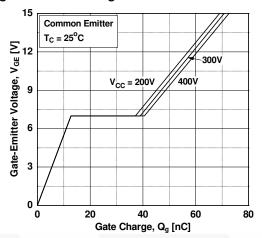


Figure 10. Turn-off Characteristics vs. Gate Resistance

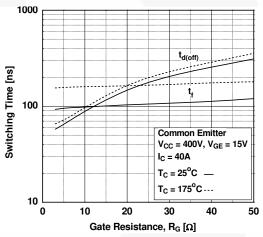
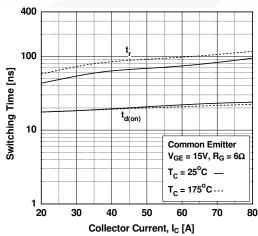


Figure 12. Turn-on Characteristics vs. Collector Current



Typical Performance Characteristics

Figure 13. Turn-off Characteristics vs. Collector Current

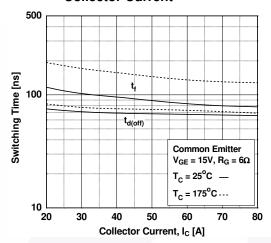


Figure 14. Switching Loss vs. Collector Current

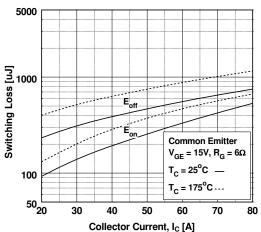


Figure 15. Load Current Vs. Frequency

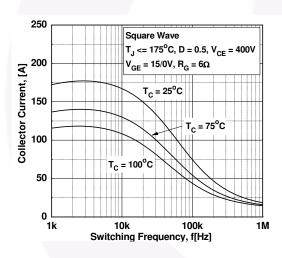


Figure 16. SOA Characteristics

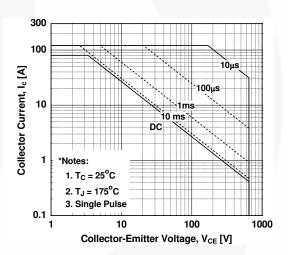
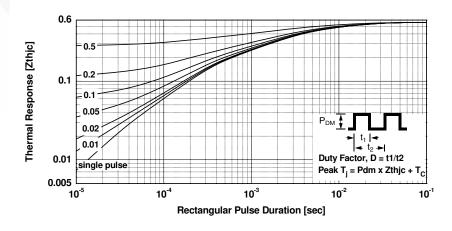
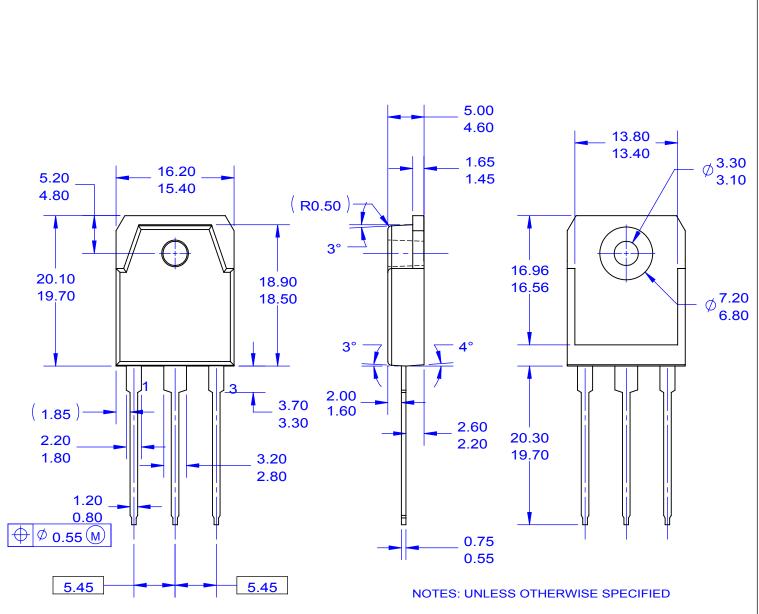
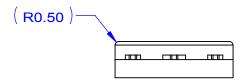


Figure 17. Transient Thermal Impedance of IGBT







- A) THIS PACKAGE CONFORMS TO EIAJ SC-65 PACKAGING STANDARD.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSION AND TOLERANCING PER ASME14.5-2009.
- D) DIMENSIONS ARE EXCLUSSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSSIONS.
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